

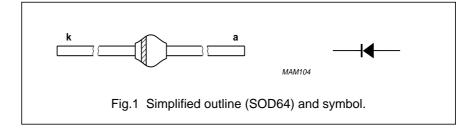
## **FEATURES**

- · Glass passivated
- Low leakage current
- · Excellent stability
- Guaranteed avalanche energy absorption capability
- Available in ammo-pack
- Also available with preformed leads for easy insertion.

#### **DESCRIPTION**

Rugged glass SOD64 package, using a high temperature alloyed construction.

This package is hermetically sealed and fatigue free as coefficients of expansion of all used parts are matched.



## **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{RRM}$	repetitive peak reverse voltage		_	600	V
$V_R$	continuous reverse voltage		_	600	V
I <sub>F(AV)</sub>	average forward current	T <sub>tp</sub> = 50 °C; lead length = 10 mm see Fig. 2; averaged over any 20 ms period; see also Fig 6	_	1.8	A
		T <sub>amb</sub> = 60 °C; PCB mounting (see Fig.10); see Fig. 3; averaged over any 20 ms period; see also Fig. 6	_	0.8	A
I <sub>FRM</sub>	repetitive peak forward current	T <sub>tp</sub> = 50 °C; see Fig. 4	_	15	А
		T <sub>amb</sub> = 60 °C; see Fig. 5	_	7	А
I <sub>FSM</sub>	non-repetitive peak forward current	t = 10 ms half sine wave; $T_j = T_{j \text{ max}}$ prior to surge; $V_R = V_{RRMmax}$	_	40	А
E <sub>RSM</sub>	non-repetitive peak reverse avalanche energy	L = 120 mH; $T_j = T_{j \text{ max}}$ prior to surge; inductive load switched off	_	10	mJ
T <sub>stg</sub>	storage temperature		-65	+175	°C
Tj	junction temperature		-65	+150	°C



## **ELECTRICAL CHARACTERISTICS**

 $T_i = 25$  °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>F</sub>	forward voltage	$I_F = 3 \text{ A}$ ; $T_j = T_{j \text{ max}}$ ; see Fig. 7	_	_	1.95	V
		I <sub>F</sub> = 3 A; see Fig. 7	_	_	3.60	V
V <sub>(BR)R</sub>	reverse avalanche breakdown voltage	I <sub>R</sub> = 0.1 mA	700	_	_	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = V <sub>RRMmax</sub> ; see Fig. 8	_	_	5	μΑ
		$V_R = V_{RRMmax}$ ; $T_j = 150$ °C; see Fig. 8	_	_	75	μΑ
t <sub>rr</sub>	reverse recovery time	when switched from $I_F = 0.5 \text{ A}$ to $I_R = 1 \text{ A}$ ; measured at $I_R = 0.25 \text{ A}$ ; see Fig. 12	-	_	15	ns
C <sub>d</sub>	diode capacitance	$f = 1 \text{ MHz}$ ; $V_R = 0 \text{ V}$ ; see Fig. 9	_	135	_	pF
$\left  \frac{dI_R}{dt} \right $	maximum slope of reverse recovery current	when switched from $I_F$ = 1 A to $V_R \ge 30$ V and $dI_F/dt$ = $-1$ A/ $\mu$ s; see Fig.11	_	_	3	A/μs

#### THERMAL CHARACTERISTICS

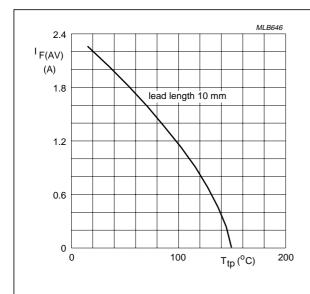
SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-tp</sub>	thermal resistance from junction to tie-point	lead length = 10 mm	25	K/W
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	75	K/W

#### Note

1. Device mounted on an epoxy-glass printed-circuit board, 1.5 mm thick; thickness of Cu-layer ≥40 μm, see Fig.10. For more information please refer to the "General Part of associated Handbook".

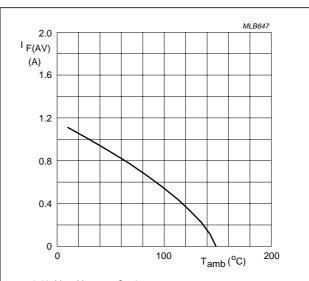


## **GRAPHICAL DATA**



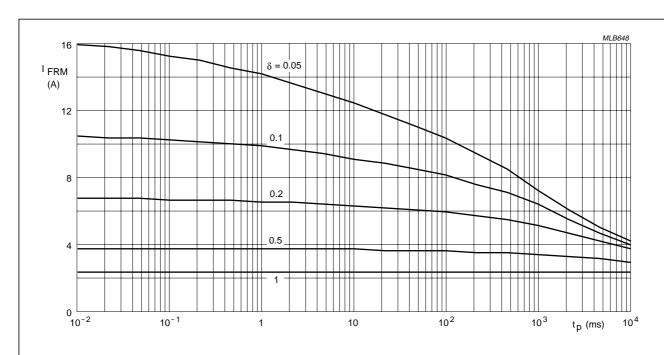
a = 1.42;  $V_R = V_{RRMmax}$ ;  $\delta = 0.5$ . Switched mode application.

Fig.2 Maximum permissible average forward current as a function of tie-point temperature (including losses due to reverse leakage).



 $\begin{aligned} &a=1.42;\ V_R=V_{RRMmax};\ \delta=0.5.\\ &\text{Device mounted as shown in Fig.10}.\\ &\text{Switched mode application}. \end{aligned}$ 

Fig.3 Maximum permissible average forward current as a function of ambient temperature (including losses due to reverse leakage).

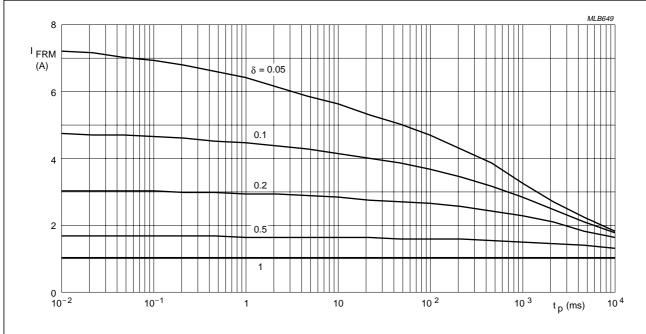


 $T_{tp}$  = 50°C;  $R_{th\ j-tp}$  = 25 K/W.

 $V_{RRMmax}$  during 1 –  $\delta;$  curves include derating for  $T_{j\,max}$  at  $V_{RRM}$  = 600 V.

Fig.4 Maximum repetitive peak forward current as a function of pulse time (square pulse) and duty factor.





$$\begin{split} &T_{amb} = 60~^{\circ}C;~R_{th~j-a} = 75~\text{K/W}.\\ &V_{RRMmax}~\text{during}~1 - \delta;~\text{curves include derating for}~T_{j~max}~\text{at}~V_{RRM} = 600~\text{V}. \end{split}$$

Fig.5 Maximum repetitive peak forward current as a function of pulse time (square pulse) and duty factor.

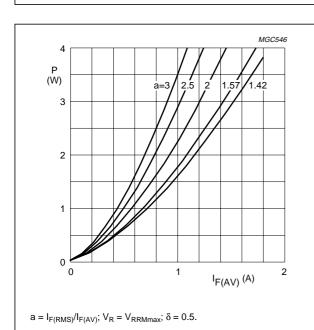
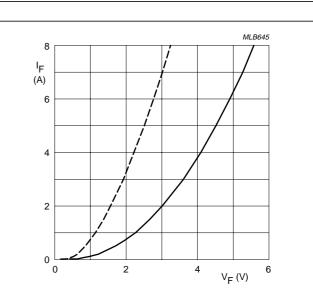


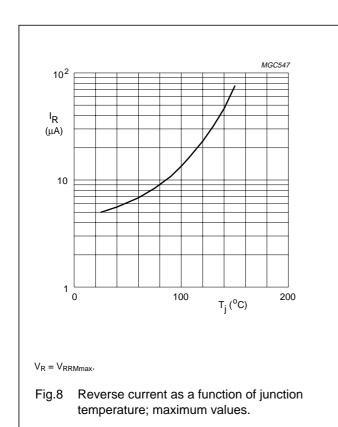
Fig.6 Maximum steady state power dissipation (forward plus leakage current losses, excluding switching losses) as a function of average forward current.

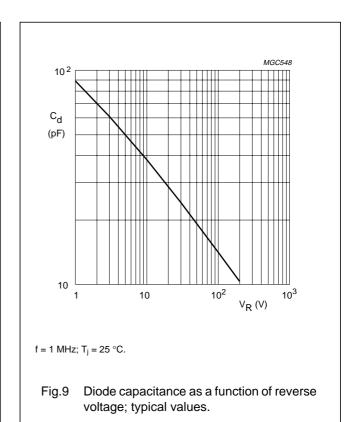


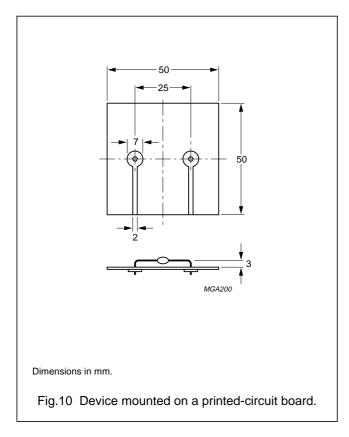
Dotted line:  $T_j = 150 \,^{\circ}\text{C}$ . Solid line:  $T_j = 25 \,^{\circ}\text{C}$ .

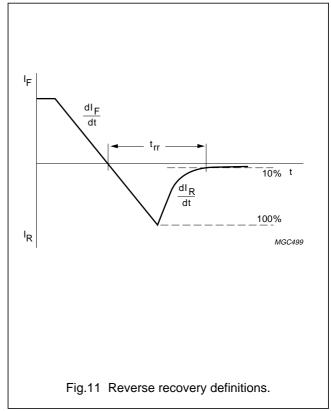
Fig.7 Forward current as a function of forward voltage; maximum values.



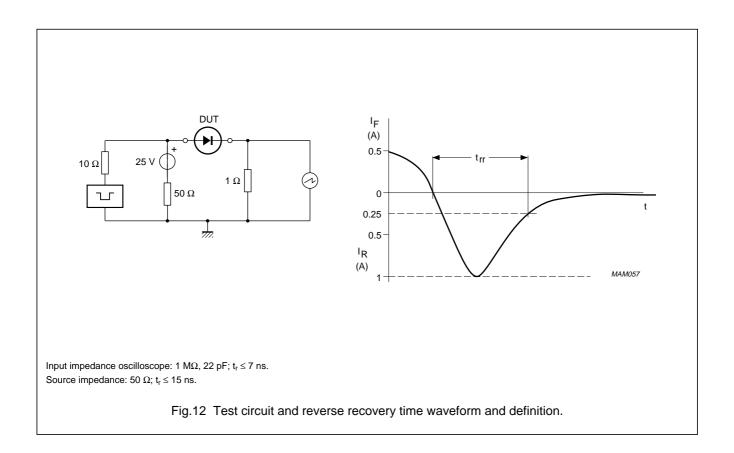












## **PACKAGE OUTLINE**

